

Technical Data Sheet

MODEL NO: Q5060R4 5060 package 5.0 x 5.5mm Red LED

Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
InGaAlP	RED	Water Clear

Electrical/Optical Characteristics(Ta=25 $^{\circ}$ C)

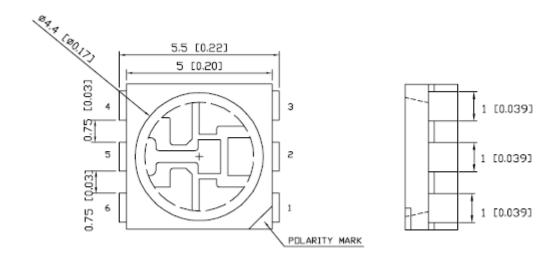
Parameter	Test	Test	Value			Unit
	Condition	Symbol	Min	Тур	Max	Uilit
Dominant wavelength	I==60mA	λО	617		629	nm
Forward voltage	I==60mA	VF	1.8		2.6	V
Luminous intensity (3 chip)	I==60mA	lv	1150		2500	mcd
Viewing angle at 50% lv	I==60mA	2 <i>\theta</i> 1/2		120		Deg
Reverse current	V _R =5V	lr			10	μА

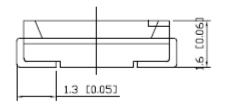


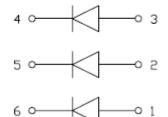
Absolute Maximum Ratings(Ta=25 $^{\circ}$ C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	62	mW
Forward current	lF	25	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+85	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/8 duty f=1kHz)	lfp	100	mA

PACKAGING DIMENSIONS (mm):







Precautions For Use:

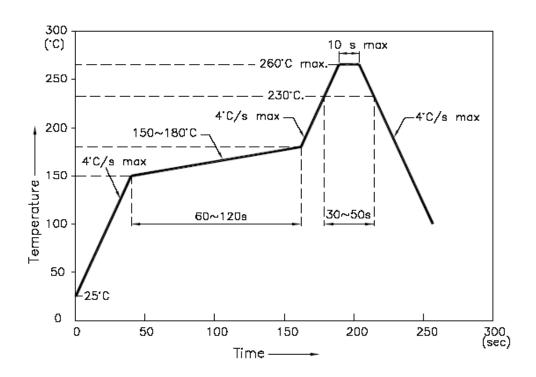
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$.the maximum soldering temperature should be limited to $260\,^{\circ}\text{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

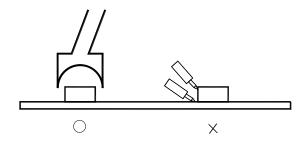


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.